Currently Configured for 300mm wafer sizes

- MFG Date: 2001.6
- Factory Interface (FI):

o Frame Config: Metro Ready

o Load-port Type: (4) Asyst S2 load port

- Polisher (L/R):

o Polishing Heads: 300mm AL Head

o Endpoint: TCM & Friction

o Platen Type (Speed): Ceramic (SIC), 10-150 RPM

o Platen Pad Conditioner: Scan Dresser 4” Disc, Sweep Driven

o Slurry Delivery: CLC Delivery

o Slurry Line1: ASAHI 25-250ml/min (low flow rate)

o Slurry Line 2: none

o Slurry Line 3: none

o Wafer Slip-out Sensor: n/a

o Platen Cooling Flow Monitor: Tokyo KEISO

o Platen Cooling Temp Monitor: User Configurable alarm Settings

o Dresser DIW Flow Meter: Flow Range 1.0-1.5 L/min

o Atomizer: Yes

- Cleaner:

o Cleaner 1 Type: Roller Brush

 Chem. Delivery Type: (1) Chem CLC 0.0-1.0 L/min (alarm capability)

 Chemical 1 Upper Flow Meter: 0.0-1.0 L/min

 Chemical 1 Lower Flow Meter: 0.0-1.0 L/min

 Bevel Edge Cleaning: n/a

o Spin Rinse Drier: Pencil Brush

 Chem. Delivery Type: (1) Chem CLC 0.0-1.0 L/min (alarm capability)

- Options:

o Robot D: Yaskawa

o Robot R: Yaskawa

o Robot L: Yaskawa

o Status Lamp (RYGB, Front/Rear)

o Monitor 1: Front

o Monitor 2: L-Side

o Monitor 3: R-Side

o EPD Monitor: R-Side

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o CPU-1 (OS/9)

o CPU-2 (OS/9)

o Touch Panel Control ver: 7.5.00

o Touch Panel Drawing ver: 7.5.00

o Online ver: 7.5.00

o ME10/ME20

- Communication:

o Controller (Logic): VME

o Controller (Process Database): Touch Panel

- Facility:

o Seismic Support: Bracket locations to be provided

o Chemical Connections: Bottom

o Exhaust Connections: Top

o Gas Connections: Bottom

o Drain Connections: Bottom